2SC3930G

Silicon NPN epitaxial planar type

For high-frequency amplification Complementary to 2SA1532G

Features

- Optimum for RF amplification of FM/AM radios
- High transition frequency f_T
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

Absolute Maximum Ratings $T_a = 25^{\circ}C$

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Parameter	Symbol	Rating	Unit			
Collector-base voltage (Emitter open)	V _{CBO}	30	V			
Collector-emitter voltage (Base open)	V _{CEO}	20	V			
Emitter-base voltage (Collector open)	V _{EBO}	5	V			
Collector current	I _C	30	mA			
Collector power dissipation	P _C	150	mW			
Junction temperature	Tj	150	°C			
Storage temperature	T _{stg}	-55 to +150	°C			

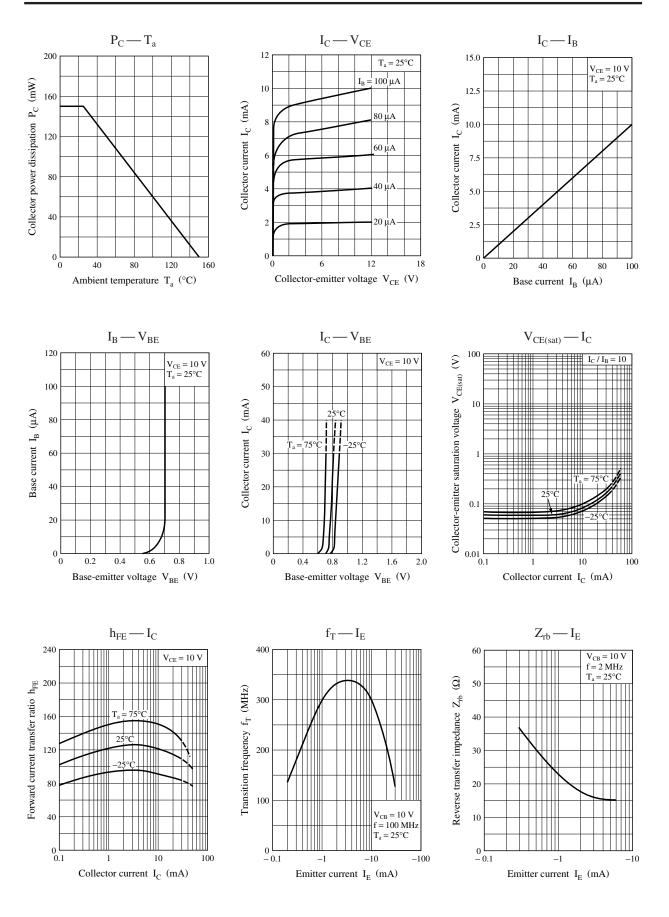
- Package
- Code
- SMini3-F2
- Marking Symbol: V
- Pin Name
 - 1. Base
 - 2. Emitter
 - 3. Collector

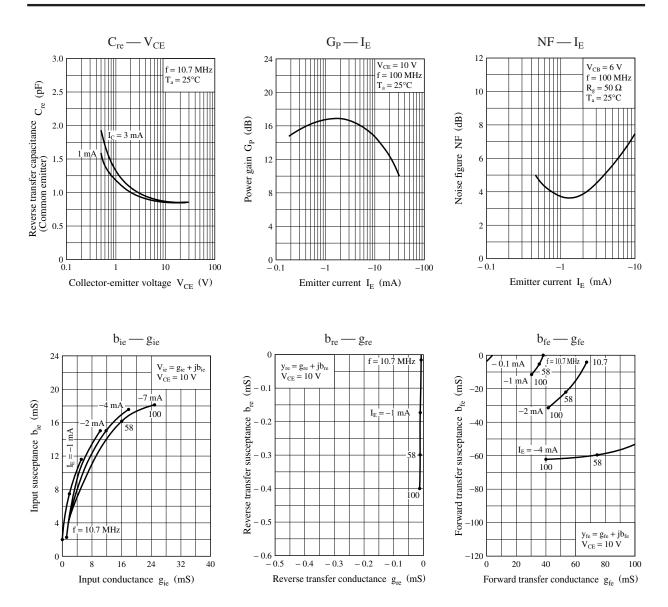
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

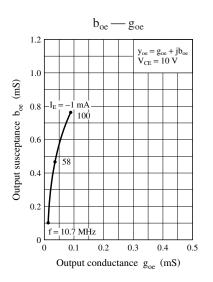
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 10 \text{ V}, I_E = 0$			0.1	μA
Forward current transfer ratio *	h _{FE}	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}$	70		220	
Transition frequency	f _T	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 200 \text{ MHz}$	150	250		MHz
Noise figure	NF	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 5 \text{ MHz}$		2.8	4.0	dB
Reverse transfer impedance	Z _{rb}	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 2 \text{ MHz}$		22	50	Ω
Reverse transfer capacitance	C _{re}	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 10.7 \text{ MHz}$		0.9	1.5	pF
(Common emitter)						

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors. 2. *: Rank classification

Rank	В	С
h _{FE}	70 to 140	110 to 220





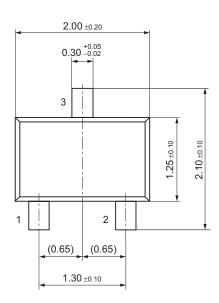


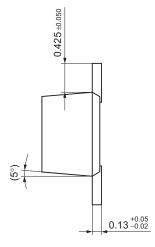
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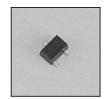
Panasonic

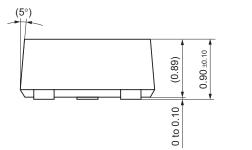
SMini3-F2

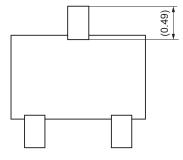
Unit: mm











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